



Material Content Data Sheet



Sales Product Name		BFP 540 H6327		Issued		25. January 2018		
MA#		MA001309868						
Package		PG-SOT343-4-2		Weight*		6.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.002	0.03		281	
	non noble metal	tin	7440-31-5	0.001	0.01		72	
	inorganic material	silicon	7440-21-3	0.014	0.21	0.25	2082	2435
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100	
	non noble metal	titanium	7440-32-6	0.003	0.05		498	
	non noble metal	chromium	7440-47-3	0.010	0.15		1493	
	non noble metal	copper	7440-50-8	3.433	49.57	49.78	495725	497816
wire	noble metal	gold	7440-57-5	0.010	0.14	0.14	1393	1393
encapsulation	organic material	carbon black	1333-86-4	0.030	0.44		4384	
	plastics	epoxy resin	-	0.653	9.42		94247	
	inorganic material	silicondioxide	60676-86-0	2.353	33.97	43.83	339729	438360
leadfinish	non noble metal	tin	7440-31-5	0.199	2.88	2.88	28768	28768
plating	noble metal	silver	7440-22-4	0.216	3.12	3.12	31228	31228
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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